



Electronics for the Future

PMDTM terminal plating Additional application for in-house plating (Application No:4022005)

June 28th ,2022

AP production Headquarters

Discreate Production Division

Power Device Engineering Department

Application content

【Overview】

For PMDTM package, we would like to apply for additional approval for in-house plating as well as outsourced plating for terminal processing points.

【Background】

It becomes difficult for outsourced companies to conduct plating processing due to the recent semiconductor shortage. Therefore, ROHM would like to apply not only outsourced plating but also in-house plating as BCP countermeasure regarding PMDTM package of RWEM.

ROHM has applied for additional approval for the in-house plating in order to maintain a stable supply of products.

【Package】

All of PMDTM (Only RWEM production)

※Due to the same situation regarding PMDUM and PMDE, we are planning to apply in September 2023

【Change content】

	RWEM(this application)	ROHM WAKO(no change)
Before	Two companies of outsourcing plating	Outsourcing plating
After	Outsourcing plating + in-house plating	Outsourcing plating

【Product name】

We do not plan to change the external model name for this addition.

If it need to take additional measures, we will consider multi-model names, so please contact us.

4M changes

【4M changes】

4M	Before(Outsourcing)	After(In house)	Change point
Man	Outsourcing operator	In house operator	Yes
Method	Deflash⇒Plating	Deflash ⇒Plating	No
Machine	Outsourcing machine	In house machine	Yes
Material	Sn100%	Sn100%	No

【Schedule】

	2022							2023									
	6	7	8	9	10	11	12	1	2	3	4	5	6	7	8	9	10
Sales meeting	◆																
Application of PMDTM				◆													
Sample				◆													
Mass product				◆													
Application of PMDUM and PMDE																	◆

* Samples will be prepared in about 8 weeks.

* If the launch of PMDUM and PMDE is accelerated, there is a possibility that the application for March 2023 will be advanced.

Result of reliability test

Conducting test type : RSA5LAMTR,RSA12LAMTR (Made in Malaysia)

※ Pretreatment : Baking (Oven_125°C×24h) ⇒Leaving at high temperature and humid (85°C×85%×168h) ⇒Reflow (Peak 250°C×3 times)

[Pn/n]

Test item		Test condition	Test time and result			
HTRB	High temperature bias	Ta=150°C、 VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
THB	High temperature and humid bias	Ta=85°C、Rh=85%、 VR=VR max	100h	240h	500h	1000h
			0/77	0/77	0/77	0/77
PCT	Pressure cooker	Ta=121°C、 Rh=100%、 2atm	100h	300h	500h	1000h
			0/77	0/77	0/77	0/77
TCY	Temperature cycle	-55°C(30min)~ +150°C(30min)	100cyc	300cyc	500cyc	1000cyc
			0/77	0/77	0/77	0/77

※It is no problem about soldability and solder wettability



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